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the substrate, said device having at least one ground connection arranged to be connected to a ground pin on a package, wherein said at least one ground connection is arranged to be connected to said ground pin using said electrical connection, where said substrate is arranged to be connected to said ground pin via a reverse side of the substrate, opposite said surface, and thereby being arranged to establish a connection between said ground connection and said ground pin.--

REMARKS

Claims 1-10 are pending in this application. By this Preliminary Amendment please cancel claim 10 without prejudice or disclaimer and add new claim 11.

If the Examiner feels that anything further will place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted,

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